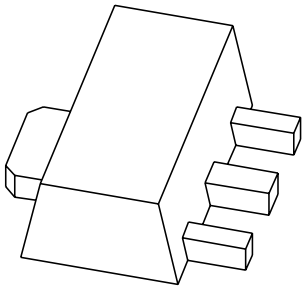
DATA SHEET



BCX51; BCX52; BCX53
PNP medium power transistors

Product specification
Supersedes data of 1999 Apr 19

2001 Oct 10

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PNP medium power transistors BCX51; BCX52; BCX53

FEATURES

- High current (max. 1 A)
- Low voltage (max. 80 V).

APPLICATIONS

- Medium power general purposes
- Driver stages of audio amplifiers.

DESCRIPTION

PNP medium power transistor in a SOT89 plastic package. NPN complements: BCX54, BCX55 and BCX56.

MARKING

TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE
BCX51	AA	BCX52-16	AM
BCX51-10	AC	BCX53	AH
BCX51-16	AD	BCX53-10	AK
BCX52	AE	BCX53-16	AL
BCX52-10	AG		

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base

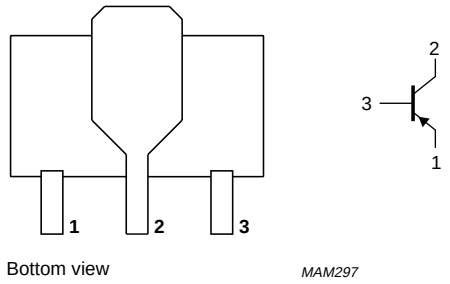


Fig.1 Simplified outline (SOT89) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BCX51		–	–45	V
	BCX52		–	–60	V
	BCX53		–	–100	V
V_{CEO}	collector-emitter voltage	open base			
	BCX51		–	–45	V
	BCX52		–	–60	V
	BCX53		–	–80	V
V_{EBO}	emitter-base voltage	open collector	–	–5	V
I_C	collector current (DC)		–	–1	A
I_{CM}	peak collector current		–	–1.5	A
I_{BM}	peak base current		–	–200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	–	1.3	W
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 6 cm^2. For other mounting conditions, see *“Thermal considerations for SOT89 in the General Part of associated Handbook”.*

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	note 1	94	K/W
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	note 1	14	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 6 cm^2. For other mounting conditions, see *“Thermal considerations for SOT89 in the General Part of associated Handbook”.*

CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CB} = –30 V	–	–	–100	nA
		I_E = 0; V_{CB} = –30 V; T_j = 125 °C	–	–	–10	µA
I_{EBO}	emitter cut-off current	I_C = 0; V_{EB} = –5 V	–	–	–100	nA
h_{FE}	DC current gain	V_{CE} = –2 V; see Fig.2				
		I_C = –5 mA	63	–	–	
		I_C = –150 mA	63	–	250	
		I_C = –500 mA	40	–	–	
	DC current gain	I_C = –150 mA; V_{CE} = –2 V; see Fig.2				
	BCX51-10; BCX52-10; BCX53-10		63	–	160	
	BCX51-16; BCX52-16; BCX53-16		100	–	250	
V_{CEsat}	collector-emitter saturation voltage	I_C = –500 mA; I_B = –50 mA	–	–	–500	mV
V_{BE}	base-emitter voltage	I_C = –500 mA; V_{CE} = –2 V	–	–	–1	V
f_T	transition frequency	I_C = –10 mA; V_{CE} = –5 V; f = 100 MHz	–	50	–	MHz

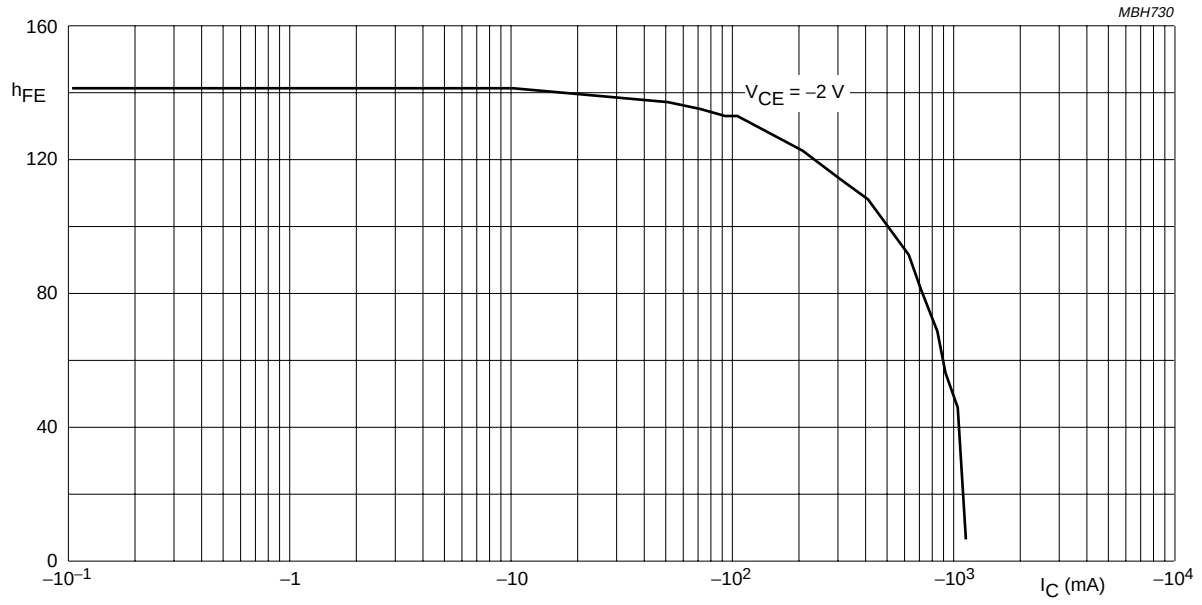
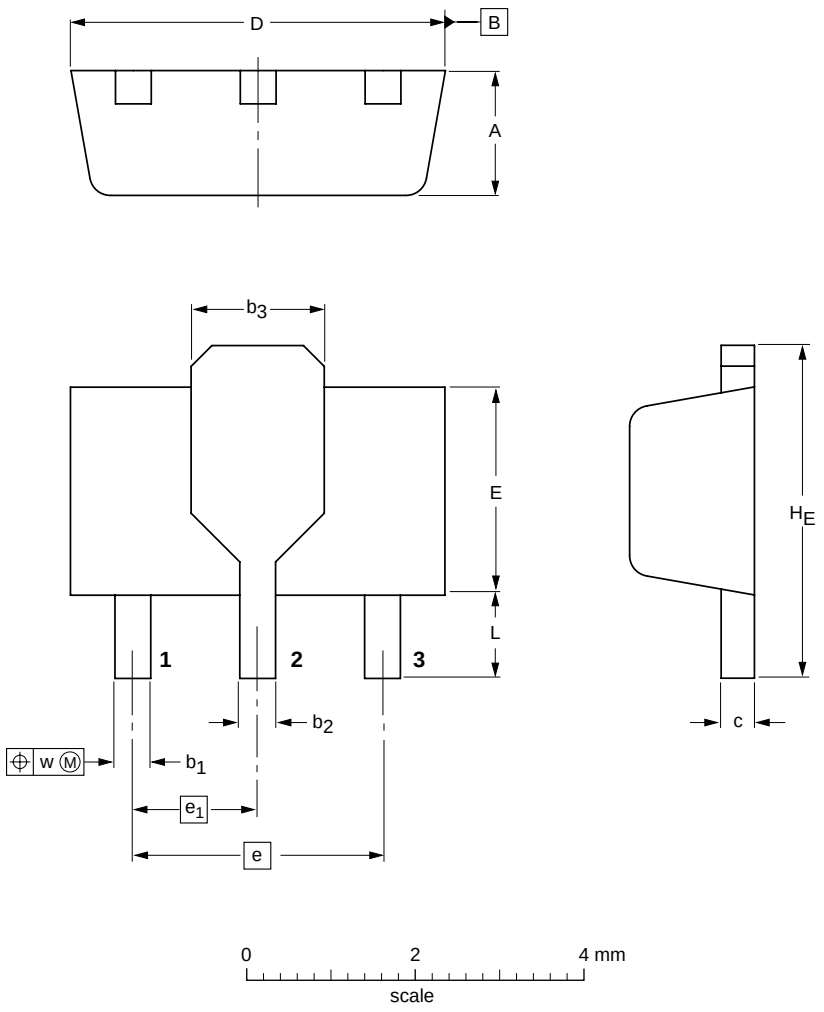


Fig.2 DC current gain; typical values.

PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 3 leads **SOT89**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b_1	b_2	b_3	c	D	E	e	e_1	H_E	L min.	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.37	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	0.8	0.13

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT89		TO-243	SC-62			~~97-02-28~~ 99-09-13

DATA SHEET STATUS

DATA SHEET STATUS[1]	PRODUCT STATUS[2]	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Printed in The Netherlands 613514/04/pp8 Date of release: 2001 Oct 10 Document order number: 9397 750 08743

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